

## Introduction To Microelectronic Fabrication Memscentral

Dear participant in the second European Workshop on Microelectronics Education, It is a pleasure to present you the Proceedings of the Second European Workshop on Microelectronics Education and to welcome you at the Workshop. The Organising Committee is very pleased that it has found several key persons, with highly appreciated levels of knowledge and expertise, willing to present Invited Contributions to this Workshop. We have striven for an interesting spread over important areas like the expected demands for educated engineers in the wide field of Microelectronics, and Microsystems, in European industry (and beyond!) and innovations in method and focus of our educational programmes. This is the second European Workshop in this area; the first one was held in Grenoble in France in the spring of 1996. It was the initiative of Georges Kamarinos, Nadine Guillemot and Bernard Courtois to organise this Workshop because they felt that Microelectronics was 'at a turning point' to become the core of the largest industry in the world and that this warranted a serious (re-)consideration of our educational imperatives. It is now two years since and their feeling has become reality: nobody doubts that by the year 2000 the microelectronics industry will be the largest industrial sector. It is also obvious that because of that and because of the predicted shortfall of educated engineers we must continuously reconsider the quality of our educational approach.

A comprehensive guide to MEMS materials, technologies and manufacturing, examining the state of the art with a particular emphasis on current and future applications. Key topics covered include: Silicon as MEMS material Material properties and measurement techniques Analytical methods used in materials characterization Modeling in MEMS Measuring MEMS Micromachining technologies in MEMS Encapsulation of MEMS components Emerging process technologies, including ALD and porous silicon Written by 73 world class MEMS contributors from around the globe, this volume covers materials selection as well as the most important process steps in bulk micromachining, fulfilling the needs of device design engineers and process or development engineers working in manufacturing processes. It also provides a comprehensive reference for the industrial R&D and academic communities. Veikko Lindroos is Professor of Physical Metallurgy and Materials Science at Helsinki University of Technology, Finland. Markku Tilli is Senior Vice President of Research at Okmetic, Vantaa, Finland. Ari Lehto is Professor of Silicon Technology at Helsinki University of Technology, Finland. Teruaki Motooka is Professor at the Department of Materials Science and Engineering, Kyushu University, Japan. Provides vital packaging technologies and process knowledge for silicon direct bonding, anodic bonding, glass frit bonding, and related techniques Shows how to protect devices from the environment and decrease package size for dramatic reduction of packaging costs Discusses properties, preparation, and growth of silicon crystals and wafers Explains the many properties (mechanical, electrostatic, optical, etc), manufacturing, processing, measuring (incl. focused beam techniques), and multiscale modeling methods of MEMS structures

The SBMicro symposium is a forum dedicated to fabrication and modeling of microsystems, integrated circuits and devices. The goal of the symposium is to bring together researchers in the areas of processing, materials, characterization, modeling and TCAD of integrated circuits, microsensors, microactuators and MEMS. This issue of ECS Transactions contains the papers presented at the 2008 conference.

Industrial electronics systems govern so many different functions that vary in complexity-from the operation of relatively simple applications, such as electric motors, to that of more complicated machines and systems, including robots and entire fabrication processes. The

Industrial Electronics Handbook, Second Edition combines traditional and new “Microsystems and Nanotechnology” presents the latest science and engineering research and achievements in the fields of microsystems and nanotechnology, bringing together contributions by authoritative experts from the United States, Germany, Great Britain, Japan and China to discuss the latest advances in microelectromechanical systems (MEMS) technology and micro/nanotechnology. The book is divided into five parts – the fundamentals of microsystems and nanotechnology, microsystems technology, nanotechnology, application issues, and the developments and prospects – and is a valuable reference for students, teachers and engineers working with the involved technologies. Professor Zhaoying Zhou is a professor at the Department of Precision Instruments & Mechanology, Tsinghua University, and the Chairman of the MEMS & NEMS Society of China. Dr. Zhonglin Wang is the Director of the Center for Nanostructure Characterization, Georgia Tech, USA. Dr. Liwei Lin is a Professor at the Department of Mechanical Engineering, University of California at Berkeley, USA.

An authoritative, systematic, and comprehensive description of current CMP technology Chemical Mechanical Planarization (CMP) provides the greatest degree of planarization of any known technique. The current standard for integrated circuit (IC) planarization, CMP is playing an increasingly important role in other related applications such as microelectromechanical systems (MEMS) and computer hard drive manufacturing. This reference focuses on the chemical aspects of the technology and includes contributions from the foremost experts on specific applications. After a detailed overview of the fundamentals and basic science of CMP, Microelectronic Applications of Chemical Mechanical Planarization: \* Provides in-depth coverage of a wide range of state-of-the-art technologies and applications \* Presents information on new designs, capabilities, and emerging technologies, including topics like CMP with nanomaterials and 3D chips \* Discusses different types of CMP tools, pads for IC CMP, modeling, and the applicability of tribometry to various aspects of CMP \* Covers nanotopography, CMP performance and defect profiles, CMP waste treatment, and the chemistry and colloidal properties of the slurries used in CMP \* Provides a perspective on the opportunities and challenges of the next fifteen years Complete with case studies, this is a valuable, hands-on resource for professionals, including process engineers, equipment engineers, formulation chemists, IC manufacturers, and others. With systematic organization and questions at the end of each chapter to facilitate learning, it is an ideal introduction to CMP and an excellent text for students in advanced graduate courses that cover CMP or related semiconductor manufacturing processes.

Focusing on recent developments in engineering science, enabling hardware, advanced technologies, and software, Micromechatronics: Modeling, Analysis, and Design with MATLAB, Second Edition provides clear, comprehensive coverage of mechatronic and electromechanical systems. It applies cornerstone fundamentals to the design of electromechanical syst

The book Smart Sensors and MEMS provides an unique collection of contributions on latest achievements in sensors area and technologies that have made by eleven internationally recognized leading experts from Czech Republic, Germany, Italy, Israel, Portugal, Switzerland, Ukraine and USA during the NATO Advanced Study Institute (ASI) in Povoá de Varzim, Portugal, from 8 to 19 September 2003. The aims of this volume are to disseminate wider and in-depth theoretical and practical knowledge about smart sensors and its applications, to create a clear consciousness about the effectiveness of MEMS technologies, advanced signal processing and conversion methods, to stimulate the theoretical and applied research in these areas, and promote the practical using of these techniques in the industry. With that in mind, a broad range of physical, chemical and biosensors design principles, technologies and applications were included in the book. It is a first attempt to describe in the same book

different physical, chemical, biological sensors and MEMS technologies suitable for smart sensors creation. The book presents the state-of-the-art and gives an excellent opportunity to provide a systematic, in-depth treatment of the new and rapidly developing field of smart sensors and MEMS. The volume is an excellent guide for practicing engineers, researchers and students interested in this crucial aspect of actual smart sensor design.

We are in the center of the most life-changing technological revolution the Earth has ever known. In little more than 65 years, an eye-blink in human history, a single technological invention has launched the proverbial thousand ships, producing the most sweeping and pervasive set of changes ever to wash over humankind; changes that are reshaping the very core of human existence, on a global scale, at a relentlessly accelerating pace. And we are just at the very beginning. *Silicon Earth: Introduction to Microelectronics and Nanotechnology* introduces readers with little or no technical background to the marvels of microelectronics and nanotechnology, using straightforward language, an intuitive approach, minimal math, and lots of pictures. The general scientific and engineering underpinnings of microelectronics and nanotechnology are described, as well as how this new technological revolution is transforming a broad array of interdisciplinary fields, and civilization as a whole. Special "widget deconstruction" chapters address the inner workings of ubiquitous micro/nano-enabled pieces of technology, such as smartphones, flash drives, and digital cameras. Completely updated and upgraded to full color, the Second Edition: Includes new material on the design of electronic systems, the future of electronics, and the societal impact of micro/nanotechnology Provides new widget deconstructions of cutting-edge tech gadgets like the GPS-enabled smartwatch Adds end-of-chapter study questions and hundreds of new color photos *Silicon Earth: Introduction to Microelectronics and Nanotechnology, Second Edition* is a pick-up-and-read-cover-to-cover book for those curious about the micro/nanoworld, as well as a classroom-tested, student-and-professor-approved text ideal for an undergraduate-level university course. Lecture slides, homework examples, a deconstruction project, and discussion threads are available via an author-maintained website.

This collection of papers examines education in microelectronics and microelectromechanical systems (MEMS).

In the past few decades, the Finite Element Method (FEM) has been developed into a key indispensable technology in the modeling and simulation of various engineering systems. The present book reports on the state of the art research and development findings on this very broad matter through original and innovative research studies exhibiting various investigation directions of FEM in electrical, civil, materials and biomedical engineering. This book is a result of contributions of experts from international scientific community working in different aspects of FEM. The text is addressed not only to researchers, but also to professional engineers, students and other experts in a variety of disciplines, both academic and industrial seeking to gain a better understanding of what has been done in the field recently, and what kind of open problems are in this area.

Society is approaching and advancing nano- and microtechnology from various angles of science and engineering. The need for further fundamental, applied, and experimental research is matched by the demand for quality references that capture the multidisciplinary and multifaceted nature of the science. Presenting cutting-edge information that is applicable to many fields, *Nano- and Micro-Electromechanical Systems: Fundamentals of Nano and Microengineering, Second Edition* builds the theoretical foundation for understanding, modeling, controlling, simulating, and designing nano- and microsystems. The book focuses on the fundamentals of nano- and microengineering and nano- and microtechnology. It emphasizes the multidisciplinary principles of NEMS and MEMS and practical applications of the basic theory in engineering practice and technology development. Significantly revised to reflect both fundamental and technological aspects, this second edition introduces the

concepts, methods, techniques, and technologies needed to solve a wide variety of problems related to high-performance nano- and microsystems. The book is written in a textbook style and now includes homework problems, examples, and reference lists in every chapter, as well as a separate solutions manual. It is designed to satisfy the growing demands of undergraduate and graduate students, researchers, and professionals in the fields of nano- and microengineering, and to enable them to contribute to the nanotechnology revolution. Whilst inkjet technology is well-established on home and small office desktops and is now having increasing impact in commercial printing, it can also be used to deposit materials other than ink as individual droplets at a microscopic scale. This allows metals, ceramics, polymers and biological materials (including living cells) to be patterned on to substrates under precise digital control. This approach offers huge potential advantages for manufacturing, since inkjet methods can be used to generate structures and functions which cannot be attained in other ways. Beginning with an overview of the fundamentals, this book covers the key components, for example piezoelectric print-heads and fluids for inkjet printing, and the processes involved. It goes on to describe specific applications, e.g. MEMS, printed circuits, active and passive electronics, biopolymers and living cells, and additive manufacturing. Detailed case studies are included on flat-panel OLED displays, RFID (radio-frequency identification) manufacturing and tissue engineering, while a comprehensive examination of the current technologies and future directions of inkjet technology completes the coverage. With contributions from both academic researchers and leading names in the industry, Inkjet Technology for Digital Fabrication is a comprehensive resource for technical development engineers, researchers and students in inkjet technology and system development, and will also appeal to researchers in chemistry, physics, engineering, materials science and electronics.

This issue of ECS Transactions is a compilation of papers presented at the 218th Meeting of the Electrochemical Society, held in Las Vegas from October 10 - 15, 2010. The papers presented covered the research and development in the field of chemical (gas, ion, bio and other) sensors, including molecular recognition surface, transduction methods, and integrated and micro sensor systems, as well as all aspects of MEMS/NEMS technology, including micro/nanomachining, fabrication processes, packaging, and the application of these structures and processes to the miniaturization of chemical sensors, physical sensors, biosensors, miniature chemical analysis systems and other devices.

Microelectromechanical systems (MEMS) is a revolutionary field that adapts for new uses a technology already optimized to accomplish a specific set of objectives. The silicon-based integrated circuits process is so highly refined it can produce millions of electrical elements on a single chip and define their critical dimensions to tolerances of 100-billionths of a meter. The MEMS revolution harnesses the integrated circuitry know-how to build working microsystems from micromechanical and microelectronic elements. MEMS is a multidisciplinary field involving challenges and opportunities for electrical, mechanical, chemical, and biomedical engineering as well as physics, biology, and chemistry. As MEMS begin to permeate more and more industrial procedures, society as a whole will be strongly affected because MEMS provide a new design technology that could rival--perhaps surpass--the societal impact of integrated circuits.

This issue of ECS Transactions features eight invited and sixty-seven regular papers on technology, devices, systems, optoelectronics, modeling and characterization; all either directly or indirectly related to microelectronics. The topics presented herein reveal the multidisciplinary character of this field, which definitely incites the highly cooperative trace of human nature. The microelectromechanical systems (MEMS) industry has experienced explosive growth over the last decade. Applications range from accelerometers and gyroscopes used in automotive safety to high-precision on-chip integrated oscillators for reference generation and mobile phones. MEMS: Fundamental Technology and Applications brings together groundbreaking



research in MEMS technology and explores an eclectic set of novel applications enabled by the technology. The book features contributions by top experts from industry and academia from around the world. The contributors explain the theoretical background and supply practical insights on applying the technology. From the historical evolution of nano micro systems to recent trends, they delve into topics including: Thin-film integrated passives as an alternative to discrete passives The possibility of piezoelectric MEMS Solutions for MEMS gyroscopes Advanced interconnect technologies Ambient energy harvesting Bulk acoustic wave resonators Ultrasonic receiver arrays using MEMS sensors Optical MEMS-based spectrometers The integration of MEMS resonators with conventional circuitry A wearable inertial and magnetic MEMS sensor assembly to estimate rigid body movement patterns Wireless microactuators to enable implantable MEMS devices for drug delivery MEMS technologies for tactile sensing and actuation in robotics MEMS-based micro hot-plate devices Inertial measurement units with integrated wireless circuitry to enable convenient, continuous monitoring Sensors using passive acousto-electric devices in wired and wireless systems Throughout, the contributors identify challenges and pose questions that need to be resolved, paving the way for new applications. Offering a wide view of the MEMS landscape, this is an invaluable resource for anyone working to develop and commercialize MEMS applications. The continued advancement of MEMS (micro-electro-mechanical systems) complexity, performance, commercial exploitation and market size requires an ever-expanding graduate population with state-of-the-art expertise. Understanding MEMS: Principles and Applications provides a comprehensive introduction to this complex and multidisciplinary technology that is accessible to senior undergraduate and graduate students from a range of engineering and physical sciences backgrounds. Fully self-contained, this textbook is designed to help students grasp the key principles and operation of MEMS devices and to inspire advanced study or a career in this field. Moreover, with the increasing application areas, product categories and functionality of MEMS, industry professionals will also benefit from this consolidated overview, source of relevant equations and extensive solutions to problems. Key features: Details the fundamentals of MEMS, enabling readers to understand the basic governing equations and know how they apply at the micron scale. Strong pedagogical emphasis enabling students to understand the fundamentals of MEMS devices. Self-contained study aid featuring problems and solutions. Book companion website hosts Matlab and PSpice codes and viewgraphs. The multi-billion-dollar microsystem packaging business continues to play an increasingly important technical role in today's information industry. The packaging process—including design and manufacturing technologies—is the technical foundation upon which function chips are updated for use in application systems, and it is an important guarantee of the continued growth of technical content and value of information systems. Introduction to Microsystem Packaging Technology details the latest advances in this vital area, which involves microelectronics, optoelectronics, RF and wireless, MEMS, and related packaging and assembling technologies. It is purposefully written so that each chapter is relatively independent and the book systematically presents the widest possible overview of packaging knowledge. Elucidates the evolving world of packaging technologies for manufacturing The authors begin by introducing the fundamentals, history, and technical challenges of microsystems. Addressing an array of design techniques for packaging and integration, they cover substrate and interconnection technologies, examples of device- and system-level packaging, and various MEMS packaging techniques. The book also discusses module assembly and optoelectronic packaging, reliability methodologies and analysis, and prospects for the evolution and future applications of microsystems packaging and

associated environmental protection. With its research examples and targeted reference questions and answers to reinforce understanding, this text is ideal for researchers, engineers, and students involved in microelectronics and MEMS. It is also useful to those who are not directly engaged in packaging but require a solid understanding of the field and its associated technologies.

A State-of-the-Art Guide to Biomedical Engineering and Design Fundamentals and Applications The two-volume Biomedical Engineering and Design Handbook, Second Edition offers unsurpassed coverage of the entire biomedical engineering field, including fundamental concepts, design and development processes, and applications. This landmark work contains contributions on a wide range of topics from nearly 80 leading experts at universities, medical centers, and commercial and law firms. Volume 1 focuses on the basics of biomedical engineering, including biomedical systems analysis, biomechanics of the human body, biomaterials, and bioelectronics. Filled with more than 500 detailed illustrations, this superb volume provides the foundational knowledge required to understand the design and development of innovative devices, techniques, and treatments. Volume 2 provides timely information on breakthrough developments in medical device design, diagnostic equipment design, surgery, rehabilitation engineering, prosthetics design, and clinical engineering. Filled with more than 400 detailed illustrations, this definitive volume examines cutting-edge design and development methods for innovative devices, techniques, and treatments. Volume 1 covers: Modeling and Simulation of Biomedical Systems Bioheat Transfer Physical and Flow Properties of Blood Respiratory Mechanics and Gas Exchange Biomechanics of the Respiratory Muscles Biomechanics of Human Movement Biomechanics of the Musculoskeletal System Biodynamics Bone Mechanics Finite Element Analysis Vibration, Mechanical Shock, and Impact Electromyography Biopolymers Biomedical Composites Bioceramics Cardiovascular Biomaterials Dental Materials Orthopaedic Biomaterials Biomaterials to Promote Tissue Regeneration Bioelectricity Biomedical Signal Analysis Biomedical Signal Processing Intelligent Systems and Bioengineering BioMEMS Volume 2 covers: Medical Product Design FDA Medical Device Requirements Cardiovascular Devices Design of Respiratory Devices Design of Artificial Kidneys Design of Controlled-Release Drug Delivery Systems Sterile Medical Device Package Development Design of Magnetic Resonance Systems Instrumentation Design for Ultrasonic Imaging The Principles of X-Ray Computed Tomography Nuclear Medicine Imaging Instrumentation Breast Imaging Systems Surgical Simulation Technologies Computer-Integrated Surgery and Medical Robotics Technology and Disabilities Applied Universal Design Design of Artificial Arms and Hands for Prosthetic Applications Design of Artificial Limbs for Lower Extremity Amputees Wear of Total Knee and Hip Joint Replacements Home Modification Design Intelligent Assistive Technology Rehabilitators Risk Management in Healthcare Technology Planning for Healthcare Institutions Healthcare Facilities Planning Healthcare Systems Engineering Enclosed Habitat Life Support The papers included in this issue of ECS Transactions were originally presented in the symposium "Microfabricated and Nanofabricated Systems for MEMS/NEMS 8", held during the PRiME 2008 meeting of The Electrochemical Society, in Honolulu, Hawaii, from October 12 to 17, 2008.

The Industrial Electronics Handbook, Second Edition combines traditional and newer,

more specialized knowledge that will help industrial electronics engineers develop practical solutions for the design and implementation of high-power applications. Embracing the broad technological scope of the field, this collection explores fundamental areas, including analog and digital circuits, electronics, electromagnetic machines, signal processing, and industrial control and communications systems. It also facilitates the use of intelligent systems—such as neural networks, fuzzy systems, and evolutionary methods—in terms of a hierarchical structure that makes factory control and supervision more efficient by addressing the needs of all production components. Enhancing its value, this fully updated collection presents research and global trends as published in the IEEE Transactions on Industrial Electronics Journal, one of the largest and most respected publications in the field. Fundamentals of Industrial Electronics covers the essential areas that form the basis for the field. This volume presents the basic knowledge that can be applied to the other sections of the handbook. Topics covered include: Circuits and signals Devices Digital circuits Digital and analog signal processing Electromagnetics Other volumes in the set: Power Electronics and Motor Drives Control and Mechatronics Industrial Communication Systems Intelligent Systems

This introductory book assumes minimal knowledge of the existence of integrated circuits and of the terminal behavior of electronic components such as resistors, diodes, and MOS and bipolar transistors. It presents to readers the basic information necessary for more advanced processing and design books. Focuses mainly on the basic processes used in fabrication, including lithography, oxidation, diffusion, ion implementation, and thin film deposition. Covers interconnection technology, packaging, and yield. Appropriate for readers interested in the area of fabrication of solid state devices and integrated circuits.

### Introduction to Microelectronic Fabrication

This book focuses on engineering design approaches for spacecraft antennas. Based on their functions in spacecraft, it discusses practical antenna design, measurement and testing. Most of the antennas covered originated at the China Academy of Space Technology (CAST), which has launched almost 300 satellites into orbit. The book presents antenna systems for seven existing spacecraft designs, while also introducing readers to new antenna technologies for spacecraft. This book is intended for researchers, graduate students, and engineers in various fields of aerospace technology and astronautics, especially spacecraft design, communication engineering and related areas.

This significant and uniquely comprehensive five-volume reference is a valuable source for research workers, practitioners, computer scientists, students, and technologists. It covers all of the major topics within the subject and offers a comprehensive treatment of MEMS design, fabrication techniques, and manufacturing methods. It also includes current medical applications of MEMS technology and provides applications of MEMS to opto-electronic devices. It is clearly written, self-contained, and accessible, with helpful standard features including an introduction, summary, extensive figures and design examples with comprehensive reference lists.

MEMS devices are finding increasingly widespread use in a variety of settings, from chemical and biological analysis to sensors and actuators in automotive applications. Along with this massive growth, the field is still experiencing growing pains as

fabrication processes are refined and new applications are attempted. Anyone serious about entering the field must have a realistic knowledge of just what is possible with MEMS technologies as well as the myriad issues involved in fabrication and device integration. *Microengineering, MEMS, and Interfacing: A Practical Guide* provides a straightforward, down-to-earth overview of the current state of MEMS technology. The first section systematically reviews the various bulk and surface micromachining methods, photolithography masks, and nonsilicon processes, examining their capabilities, limitations, and suggested uses. Next, the author details the characteristics of individual devices and systems, their advantages and shortcomings, and how they can be combined to achieve desired functionality. He includes condensed introductions to relevant chemistry and biochemistry and then demonstrates applications of MEMS in these areas. Beginning with a short introduction to electronics, the final section explores the issues involved in interfacing MEMS components with other systems. With judicious use of illustrations to clarify the discussion, *Microengineering, MEMS, and Interfacing: A Practical Guide* offers hands-on tools for solving specific problems along with the insight necessary to use them most effectively.

As our knowledge of MEMS continues to grow, so does *The MEMS Handbook*. The field has changed so much that this Second Edition is now available in three volumes. Individually, each volume provides focused, authoritative treatment of specific areas of interest. Together, they comprise the most comprehensive collection of MEMS knowledge available, packaged in an attractive slipcase and offered at a substantial savings. This best-selling handbook is now more convenient than ever, and its coverage is unparalleled. The first of three volumes, *MEMS: Introduction and Fundamentals* covers the theoretical and conceptual underpinnings of the field, emphasizing the physical phenomena that dominate at the micro-scale. It also explores the mechanical properties of MEMS materials, modeling and simulation of MEMS, control theory, and bubble/drop transport in microchannels. Chapters were updated where necessary, and the book also includes two new chapters on microscale hydrodynamics and lattice Boltzmann simulations. This volume builds a strong foundation for further study and work in the MEMS field. *MEMS: Introduction and Fundamentals* comprises contributions from the foremost experts in their respective specialties from around the world. Acclaimed author and expert Mohamed Gad-el-Hak has again raised the bar to set a new standard for excellence and authority in the fledgling fields of MEMS and nanotechnology.

Polycrystalline SiGe has emerged as a promising MEMS (Microelectromechanical Systems) structural material since it provides the desired mechanical properties at lower temperatures compared to poly-Si, allowing the direct post-processing on top of CMOS. This CMOS-MEMS monolithic integration can lead to more compact MEMS with improved performance. The potential of poly-SiGe for MEMS above-aluminum-backend CMOS integration has already been demonstrated. However, aggressive interconnect scaling has led to the replacement of the traditional aluminum metallization by copper (Cu) metallization, due to its lower resistivity and improved reliability. Poly-SiGe for MEMS-above-CMOS sensors demonstrates the compatibility of poly-SiGe with post-processing above the advanced CMOS technology nodes through the successful fabrication of an integrated poly-SiGe piezoresistive pressure sensor, directly fabricated above 0.13  $\mu\text{m}$  Cu-backend CMOS. Furthermore, this book presents the first detailed



investigation on the influence of deposition conditions, germanium content and doping concentration on the electrical and piezoresistive properties of boron-doped poly-SiGe. The development of a CMOS-compatible process flow, with special attention to the sealing method, is also described. Piezoresistive pressure sensors with different areas and piezoresistor designs were fabricated and tested. Together with the piezoresistive pressure sensors, also functional capacitive pressure sensors were successfully fabricated on the same wafer, proving the versatility of poly-SiGe for MEMS sensor applications. Finally, a detailed analysis of the MEMS processing impact on the underlying CMOS circuit is also presented.

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